ABSTRACT

FORCE MEASUREMENT DEVICE INCORPORATED IN AN ELECTRONIC COMPONENT PROCESSING APPARATUS

A device for measuring a force applied to a component when the component is being bonded to a component carrier, or when the component is being encapsulated includes a deformable portion and a contacting stem connected to the deformable portion. The deformable portion is configured to incorporate a sensor for detecting a degree of deformation of the deformable portion caused by application of the force in order to measure the force. In use, the contacting stem is positionable to contact the component or the component carrier so that the deformable portion is deformed when the force is applied to the component. One or more such devices may be included in a sintering or encapsulation apparatus for measuring the said force.

[FIG. 2]